



Semiconductor Device Type: (Q6A) 064_VQFN 8x8x0.9mm MatteTin						Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			J-STD-609A Product Marking and/or Pkg. Labeling e3
Basic Substance	CAS Number	Contained in* Sub-Component	% Total Weight	mg/part	ppm	90.05	(mg) Total	Mold Compound	% of Total Weight	50.73		
Silica Fused	60676-86-0	Mold Compound	44.779	79.483	447,794	90.05	(mg) Total	Mold Compound	% of Total Weight	50.73		
Epoxy Resin	Trade Secret	Mold Compound	3.166	5.619	31,656							
Phenol Resin	Trade Secret	Mold Compound	2.633	4.673	26,329							
Carbon Black	1333-86-4	Mold Compound	0.152	0.270	1,522							
Copper	7440-50-8	Lead Frame	42.849	76.056	428,486							
Iron	7439-89-6	Lead Frame	1.054	1.871	10,540	79.61	(mg) Total	Lead Frame	% of Total Weight	44.85		
Silver	7440-22-4	Lead Frame	0.854	1.517	8,544							
Zinc	7440-66-6	Lead Frame	0.056	0.100	561							
Phosphorous	7723-14-0	Lead Frame	0.037	0.066	370							
Silver	7440-22-4	Die Attach	0.200	0.355	2,002							
Acrylic Resin	Trade secret	Die Attach	0.036	0.065	364	0.46	(mg) Total	Die Attach	% of Total Weight	0.26		
Epoxy Resin	Trade secret	Die Attach	0.023	0.042	234							
Silicon	7440-21-3	Chip (Die)	1.810	3.213	18,100							
Gold	7440-57-5	Wire Bond	0.510	0.905	5,100							
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.840	3.266	18,400							
TOTALS:			100.000	177.500	1,000,000							
0.1775 g Total Mass												
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)						3.21	Total (mg)	Chip (Die)	% of Total Weight	1.81		
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and/or analytical test data.												
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.												
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/en/pages/offers/industries/chemicals/plastics/												
The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.												
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table												
						0.91	(mg) Total	Wire Bond	% of Total Weight	0.51		
						Gold 7440-57-5 100.00						
						Total 100.00						
						3.27	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.84		
						Tin 7440-31-5 100.00						
						Total 100.00						

177.50

100.00